CLAIMS

1. A method of packaging components, comprising:

bonding a carrier to an enclosure including a plurality of covers having an aircavity to receive at least one of the components therein; and

forming a component package assembly.

- 2. The method of claim 1, wherein the components comprise at least one component die.
- 3. The method of claim 1, wherein the enclosure is formed of materials comprising polymers, ceramic, glass, and combinations thereof.
- 4. The method of claim 1, wherein bonding comprises providing an adhesive layer between the enclosure and the carrier.
- 5. The method of claim 4, wherein providing the adhesive layer between the enclosure and the carrier comprises applying an adhesive to the carrier.
- 6. The method of claim 4, wherein providing an adhesive layer between the enclosure and the carrier comprises applying adhesive to a cover surface disposed adjacent the carrier.
- 7. The method of claim 1, further comprising separating the component package assembly into a plurality of individual component packages.
- 8. The method of claim 7, wherein separating comprises cutting between each of the pluralities of component through a plurality of sidewalls and the carrier.
- 9. The method of claim 8, wherein cutting comprises sawing, laser cutting, water

cutting, milling, machining, lathing, and combinations thereof.

10. A method of packaging components, comprising:

bonding a body including a plurality of component covers to a carrier comprising a plurality of the components thereon wherein at least one of the components is positioned proximate one of the component covers; and

providing an air-cavity between the components and a respective component covers.

- 11. The method of claim 10, wherein the components comprise an component die.
- 12. The method of claim 10, wherein the body is formed of materials comprising polymers, ceramic, glass, and combinations thereof.
- 13. The method of claim 10, wherein the body comprises sidewalls defining the component covers.
- 14. The method of claim 13, wherein bonding the body to the carrier comprises providing an adhesive between the sidewalls and the carrier.
- 15. The method of claim 10, further comprising separating the sidewalls and carrier to form individual components having at least one of the plurality of covers thereon.
- 16. The method of claim 15, wherein separating comprises sawing the common sidewalls and carrier using a saw, laser cutting tool, water cutting tool, mill, lath, and combinations thereof.
- 17. The method of claim 10, wherein providing the air-cavity between each of the components and their respective component covers comprises forming the sidewalls with a top portion that exceeds the height of the components.

- 18. The method of claim 17, wherein the sidewalls and the top portion define an enclosure.
- 19. An apparatus for enclosing at least one component, comprising:
- a plurality of separable sidewalls disposed on a top member wherein the separable sidewalls and top member define a plurality of separable individual component packages to enclose the at least one component therein.
- 20. The apparatus of claim 19, wherein when separated, the sidewalls and top member define an individual component enclosure.